

GSM2301

20V P-Channel Enhancement Mode MOSFET

Product Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

These devices are well suited for high efficiency fast switching applications.

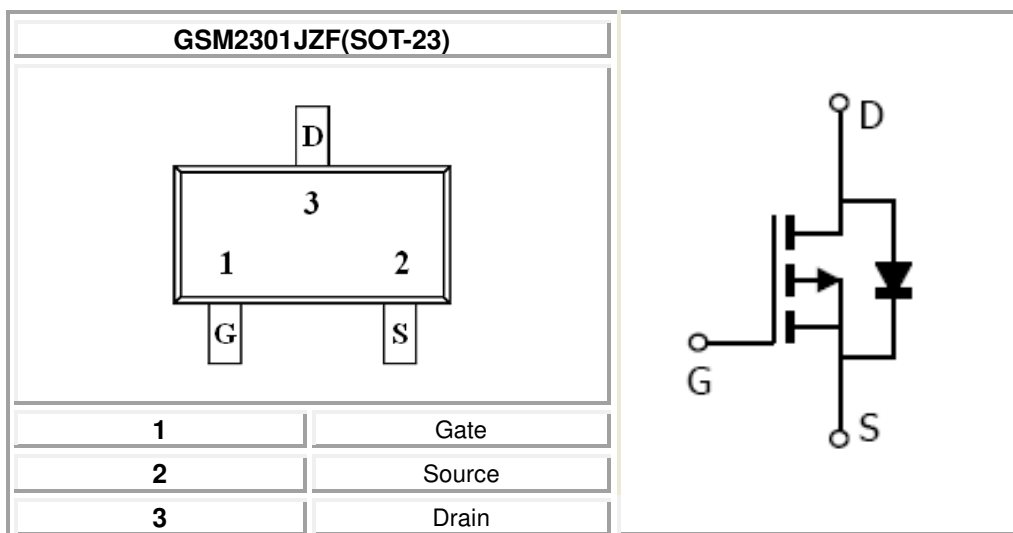
Features

- -20V/-2.8A, $R_{DS(ON)}=130m\Omega@V_{GS}=-4.5V$
- improved dv/dt capability
- Fast switching
- Green Device Available
- Suit for -1.8V Gate Drive Applications

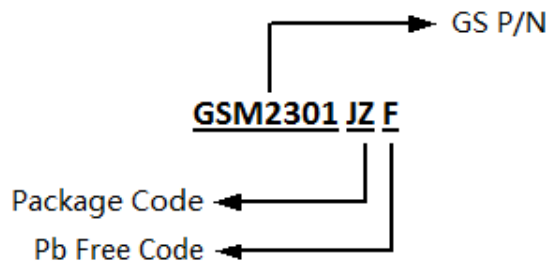
Applications

- Power Management in Notebook
- Load Switch
- Hand-Held instruments

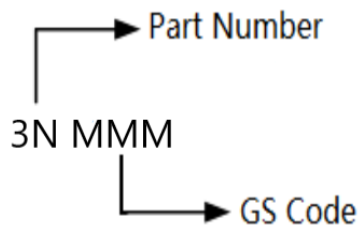
Packages & Pin Assignments



Ordering Information



Marking Information



| Part Number | Package | Part Marking |
|-------------|---------|--------------|
| GSM2301JZF | SOT-23 | 3NMMM |

Absolute Maximum Ratings

(T_C=25°C unless otherwise noted)

| Symbol | Parameter | Typical | Unit |
|------------------|--|-----------------------|-------|
| V _{DSS} | Drain-Source Voltage | -20 | V |
| V _{GSS} | Gate –Source Voltage | ±10 | V |
| I _D | Continuous Drain Current | T _C =25°C | -2.8 |
| | | T _C =100°C | -1.8 |
| I _{DM} | Pulsed Drain Current ¹ | -10 | A |
| P _D | Power Dissipation | T _C =25°C | 1.56 |
| | Power Dissipation – Derate above 25°C | | 0.012 |
| T _J | Operating Junction Temperature Range | -55 to 150 | °C |
| T _{STG} | Storage Temperature Range | -55 to 150 | °C |
| R _{θJA} | Thermal Resistance-Junction to Ambient | 80 | °C/W |

Electrical Characteristics

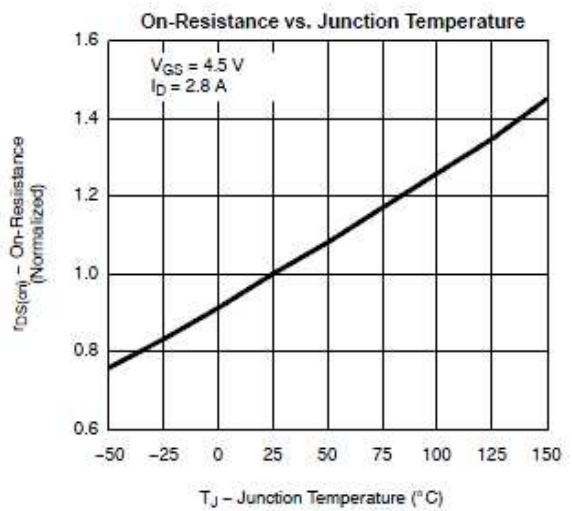
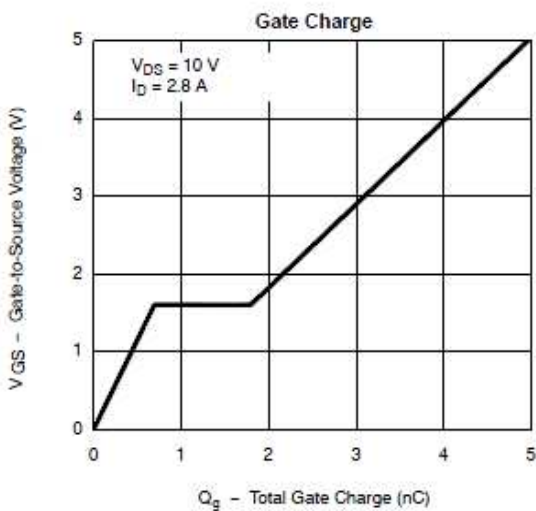
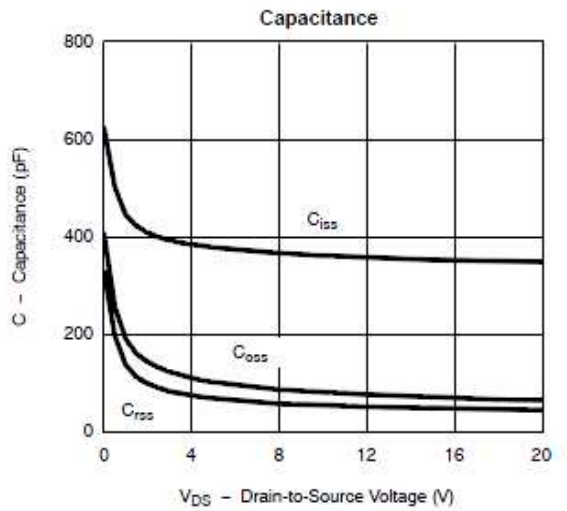
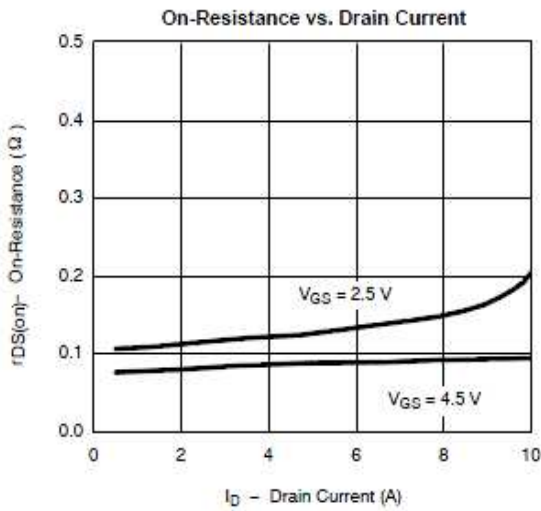
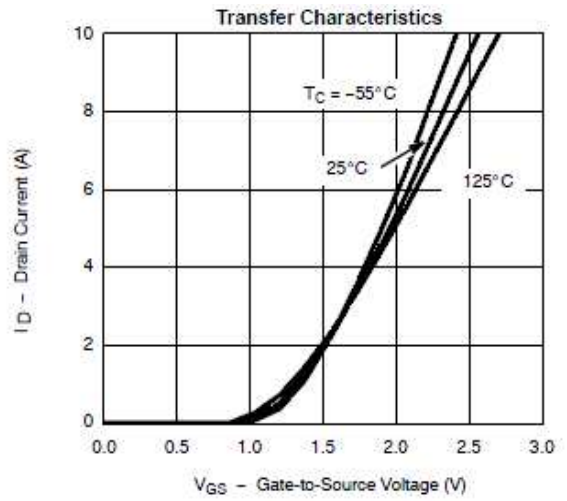
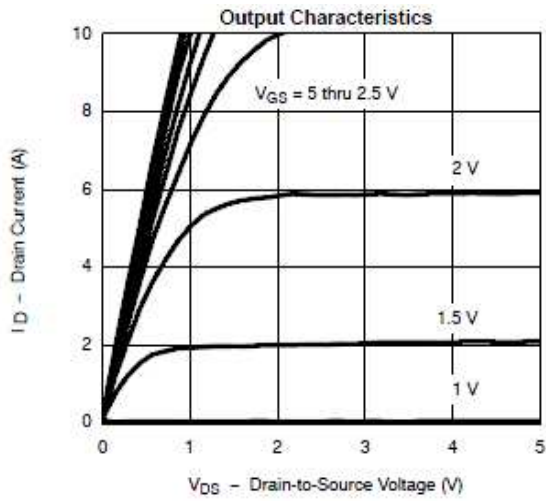
(T_J=25°C unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Typ | Max. | Unit | |
|----------------------|-----------------------------------|--|------------------------------|------|------|------|----|
| Static | | | | | | | |
| V _{(BR)DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =-250uA | -20 | | | V | |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} = V _{GS} , I _D =-250uA | -0.3 | -0.6 | -1.0 | | |
| I _{GSS} | Gate Source Leakage Current | V _{DS} =0V, V _{GS} =±10V | | | ±100 | nA | |
| I _{DSS} | Drain Source Leakage Current | V _{DS} =-20V, V _{GS} =0V | | | -1 | uA | |
| R _{DS(on)} | Drain-Source On-Resistance | V _{GS} =-4.5V, I _D =-2.8A | | 96 | 130 | mΩ | |
| | | V _{GS} =-2.5V, I _D =-2.0A | | 140 | 190 | | |
| | | V _{GS} =-1.8V, I _D =-1.0A | | 192 | 260 | | |
| V _{SD} | Diode Forward Voltage | I _S =-1A, V _{GS} =0V | | | -1 | V | |
| I _S | Continuous Source Current | V _G =V _D =0V | | | -2.5 | A | |
| Dynamic | | | | | | | |
| Q _g | Total Gate Charge ^{2,3} | V _{DS} =-10V, V _{GS} =-4.5V I _D ≡-1A | | 2.5 | 5 | nC | |
| Q _{gs} | Gate-Source Charge ^{2,3} | | | 0.36 | 0.72 | | |
| Q _{gd} | Gate-Drain Charge ^{2,3} | | | 0.5 | 1.0 | | |
| C _{iss} | Input Capacitance | V _{DS} =-15V, V _{GS} =0V f=1MHz | | 150 | 300 | pF | |
| C _{oss} | Output Capacitance | | | 32 | 64 | | |
| C _{rss} | Reverse Transfer Capacitance | | | 23 | 46 | | |
| t _{d(on)} | Turn-On Time ^{2,3} | V _{DD} =-10V, I _D ≡-1.0A, V _{GS} =-4.5V, R _G =25Ω | | 2 | 4 | ns | |
| t _r | | | | 7.8 | 15 | | |
| t _{d(off)} | | | Turn-Off Time ^{2,3} | | 16.6 | | 32 |
| t _f | | | | | 4.5 | | 9 |

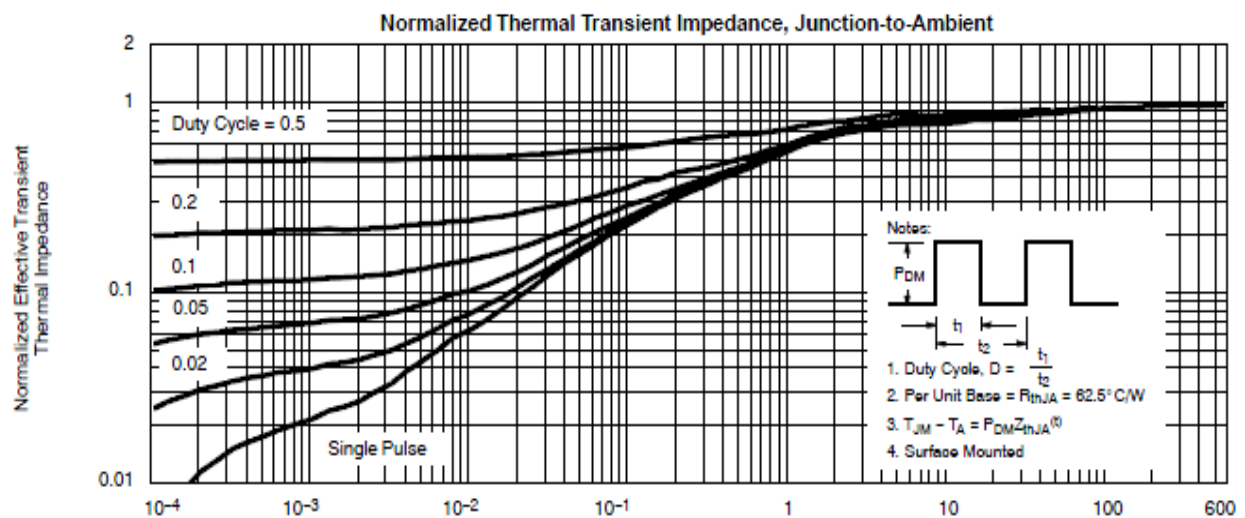
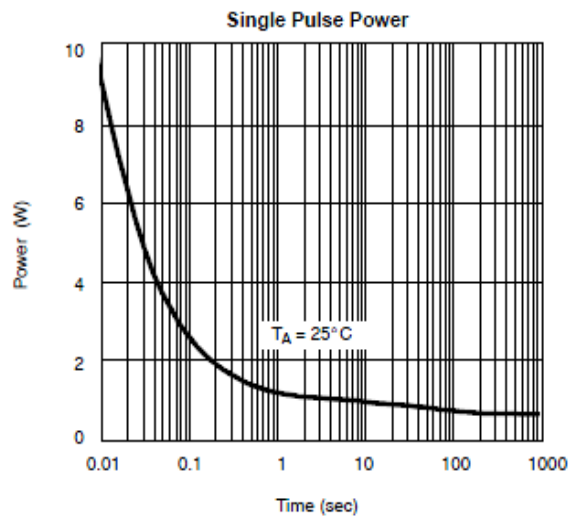
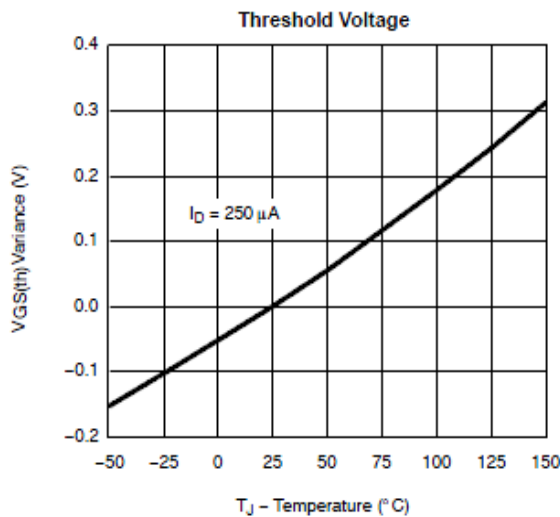
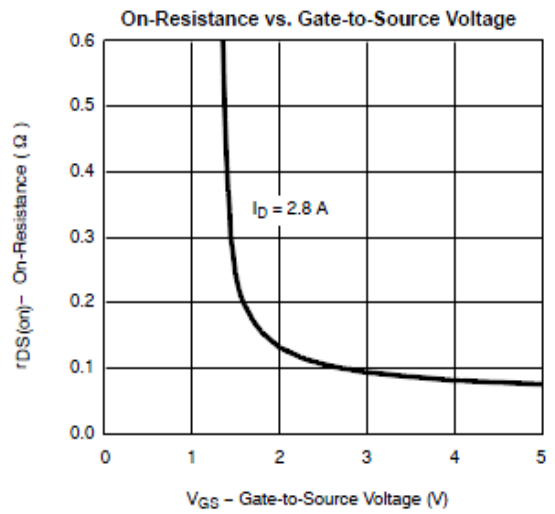
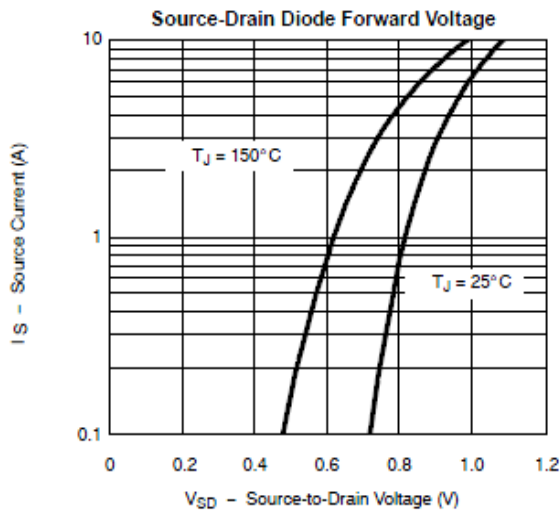
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
3. Essentially independent of operating temperature.

Typical Performance Characteristics

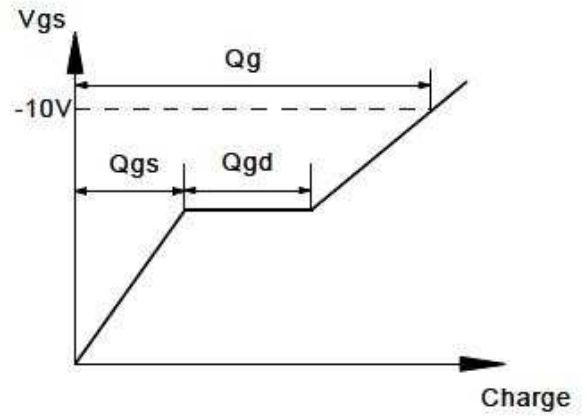
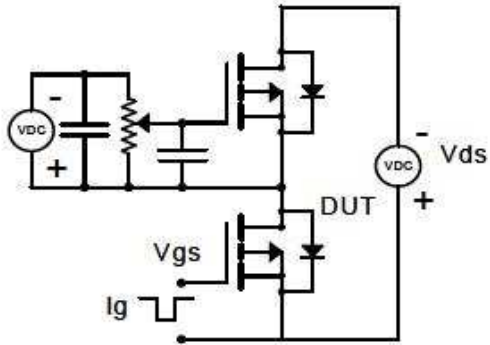


Typical Performance Characteristics (continue)

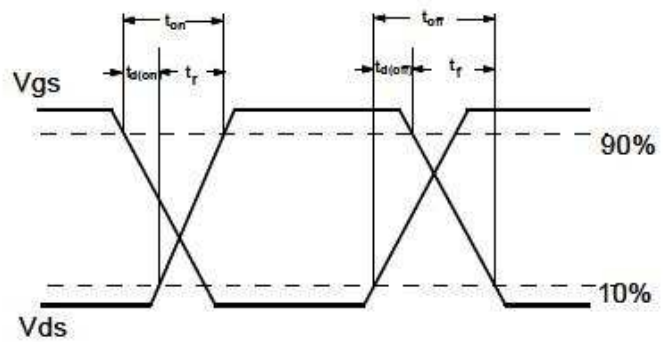
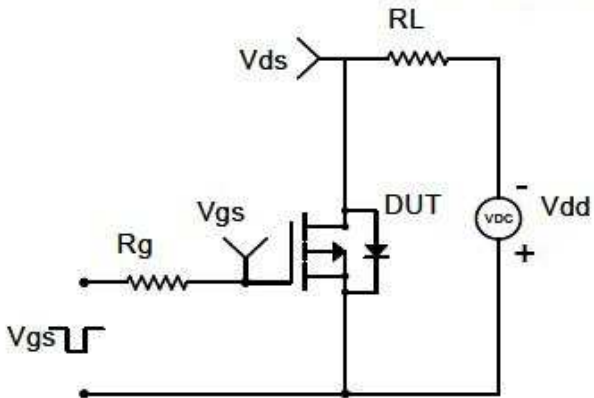


Typical Characteristics

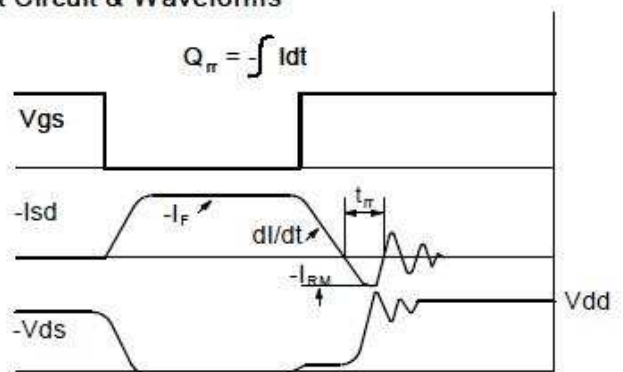
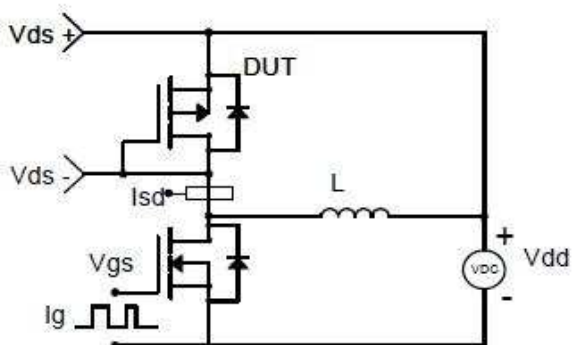
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

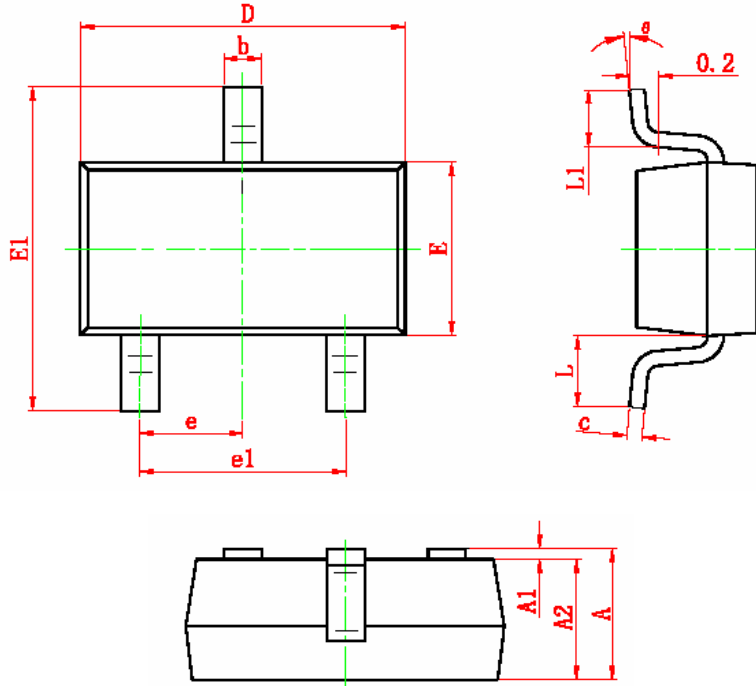


Diode Recovery Test Circuit & Waveforms



Package Dimension

SOT-23









| Dimensions | | | | |
|------------|-------------|-------|-----------|-------|
| SYMBOL | Millimeters | | Inches | |
| | MIN | MAX | MIN | MAX |
| A | 0.900 | 1.200 | 0.035 | 0.043 |
| A1 | 0.000 | 0.100 | 0.000 | 0.004 |
| A2 | 0.900 | 1.100 | 0.035 | 0.039 |
| b | 0.300 | 0.500 | 0.012 | 0.020 |
| c | 0.080 | 0.150 | 0.003 | 0.006 |
| D | 2.800 | 3.000 | 0.110 | 0.118 |
| E | 1.200 | 1.400 | 0.047 | 0.055 |
| E1 | 2.250 | 2.550 | 0.089 | 0.100 |
| e | 0.950 TYP | | 0.037 TYP | |
| e1 | 1.800 | 2.000 | 0.071 | 0.079 |
| L | 0.550 REF | | 0.022 REF | |
| L1 | 0.300 | 0.500 | 0.012 | 0.020 |
| θ | 0° | 8° | 0° | 8° |

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CONTACT US

| GS Headquarter | |
|---|--|
|  | 4F.,No.43-1,Lane11,Sec.6,Minquan E.Rd Neihu District Taipei City 114, Taiwan (R.O.C) |
|  | 886-2-2657-9980 |
|  | 886-2-2657-3630 |
|  | sales_twn@gs-power.com |

| RD Division | |
|---|--------------------------------------|
|  | 824 Bolton Drive Milpitas. CA. 95035 |
|  | 1-408-457-0587 |